

# POLI-762 CMP Tool with Membrane Carrier

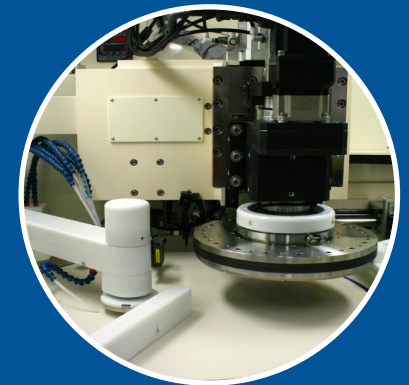


The G&P Technology POLI-762 Membrane Carrier CMP Tool is our most advanced and intelligent CMP tool designed for high versatility for 12"(300mm) CMP process development, materials evaluation and pre-production runs. The POLI-762 was also designed for advanced wafer manufactures and consumables suppliers.

## FEATURES

Programmable control of:

- Wafer size capacity up to 300mm
- Rotational speed of the polishing platen & wafer carrier
- Swing arm style pad conditioner
- Downforce of the pad conditioning disk
- Programmable sweep speed of the conditioning arm
- Oscillation of the wafer carrier on the polishing pad
- Teflon coated polishing table
- 3 Slurry pumps



The POLI-762 Swing Arm Conditioning System for optimized CMP processing

DIMENSIONS			FACILITIES	
Metric	1580W x 1480D x 1960H		Power	220VAC, 3PH, 70A
Inches	62.5W x 58.3D x 77H		DI Water	2 l/min avg, 10 l/min peak
Weight	~2756 kg	6063 lbs	CDA	5 SCFM
			Exhaust	100 CFM

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STANDARD CONFIGURATION - Model POLI-762		
Wafer size capacity	Up to 300mm	Up to 12"
1 polishing platen	Hard Anodized Aluminum w/Teflon coating	
Diameter	762mm	30"
Speed range	30 - 200 rpm	
Number of wafer carriers	1	
Speed range	30 - 200 rpm	
Membrane type w/ring control	Front referencing	
Oscillation range	±12mm	±0.5"
Pad conditioner	Swing arm style is standard	
Slurry pumps	3	
Operator interface	Intuitive touch screen	
Loading system	Manual load/unload	
Table rinse spray	High pressure spray system	
Platen temperature control	Standard (customer provides chiller)	
Machine process housing	Stainless Steel/Cleanroom compatible	

OPTIONS AVAILABLE	
Second wafer carrier	Optional
Special wafer carrier type	Optional
Type	5-pressure zones
Feature	Programmable ring pressure adjust
Pad profiling system	To control pad shape
Low pressure polishing system	For copper & low K applications
End point systems	Motor current/Frictional force
	Temperature
Loading system	Semi-automatic

## CONDITIONING ARM OPTIONS

- Swing Arm Conditioning  
(radial sweep)
- 100mm end effector (standard), 30-200 rpm range
  - Downforce range, .45 - 9.1kgf (1 - 20 lbf)
  - Sweep zone control, 8 segments
  - Sweep rate, 0 - 20 sweep/minute
  - Conditioning disk clean station

